

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - ambient	R_{thJA}	minimal footprint ⁽²⁾	-	-	250	K/W
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Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified
Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=250\text{ }\mu\text{A}$	20	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=11\text{ }\mu\text{A}$	0.6	0.95	1.2	
Drain-source leakage current	I_{DSS}	$V_{DS}=20\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$	-	-	1	μA
		$V_{DS}=20\text{ V}, V_{GS}=0\text{ V}, T_j=150\text{ °C}$	-	-	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=12\text{ V}, V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=2.5\text{ V}, I_D=1.95\text{ A}$	-	62	85	$\text{m}\Omega$
		$V_{GS}=4.5\text{ V}, I_D=2.5\text{ A}$	-	39	50	
Transconductance	g_{fs}	$ V_{DS} >2 I_D R_{DS(on)max}, I_D=2\text{ A}$	-	8.6	-	S

⁽²⁾ Performed on 40mm² FR4 PCB. The traces are 1mm wide, 70 μm thick and 20mm long; they are present on both sides of the PCB.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=10\text{ V},$ $f=1\text{ MHz}$	-	315	419	pF
Output capacitance	C_{oss}		-	114	152	
Reverse transfer capacitance	C_{rss}		-	16	24	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=10\text{ V}, V_{GS}=4.5\text{ V},$ $I_D=2.5\text{ A}, R_{G,ext}=6\text{ }\Omega$	-	5.8	-	ns
Rise time	t_r		-	2.9	-	
Turn-off delay time	$t_{d(off)}$		-	11.0	-	
Fall time	t_f		-	2.4	-	

Gate Charge Characteristics

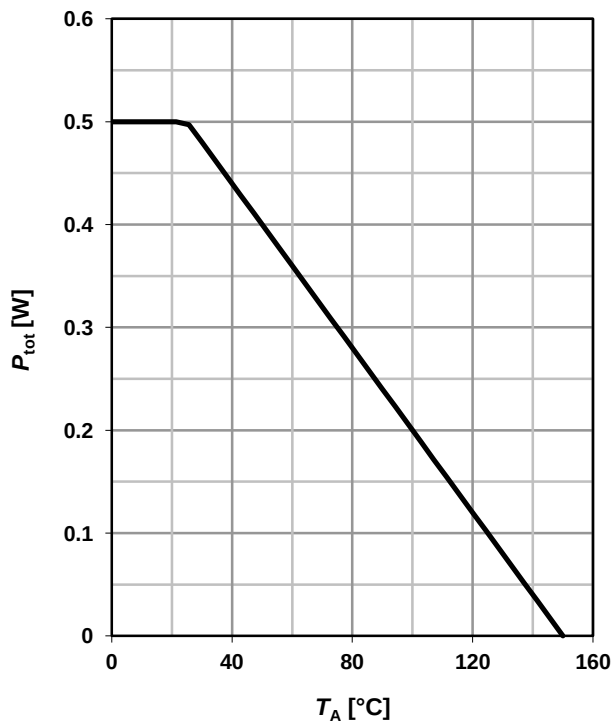
Gate to source charge	Q_{gs}	$V_{DD}=10\text{ V}, I_D=2.5\text{ A},$ $V_{GS}=0\text{ to }4.5\text{ V}$	-	0.65	0.86	nC
Gate to drain charge	Q_{gd}		-	0.5	0.7	
Gate charge total	Q_g		-	2.1	3.2	
Gate plateau voltage	$V_{plateau}$		-	2	-	V

Reverse Diode

Diode continuous forward current	I_S	$T_A=25\text{ }^\circ\text{C}$	-	-	0.5	A
Diode pulse current	$I_{S,pulse}$		-	-	10	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=2.5\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	0.8	1.1	V
Reverse recovery time	t_{rr}	$V_R=10\text{ V}, I_F=2.5\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	10	-	ns
Reverse recovery charge	Q_{rr}		-	2.2	-	nC

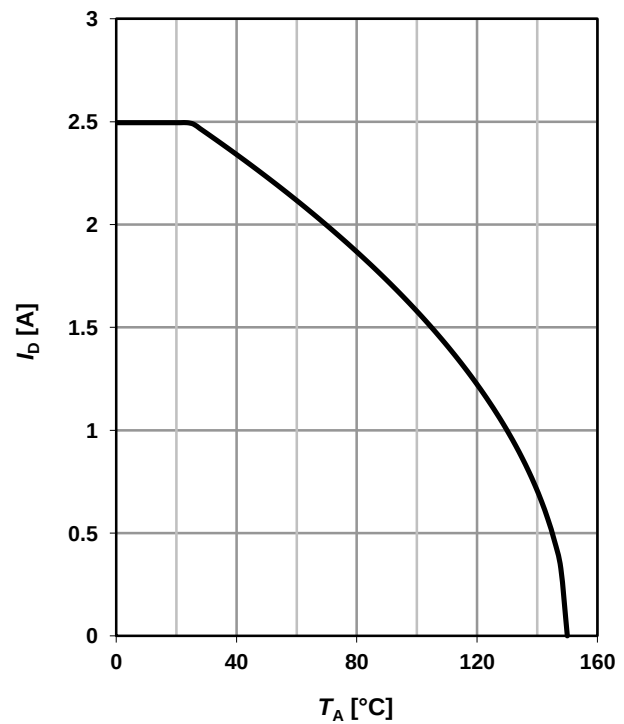
1 Power dissipation

$$P_{\text{tot}} = f(T_A)$$



2 Drain current

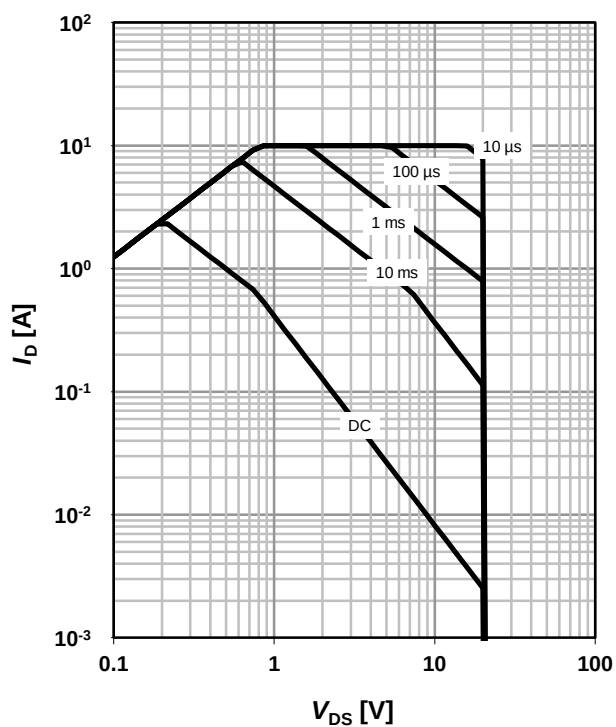
$$I_D = f(T_A); V_{GS} \geq 4.5 \text{ V}$$



3 Safe operating area

$$I_D = f(V_{DS}); T_A = 25^\circ\text{C}; D = 0$$

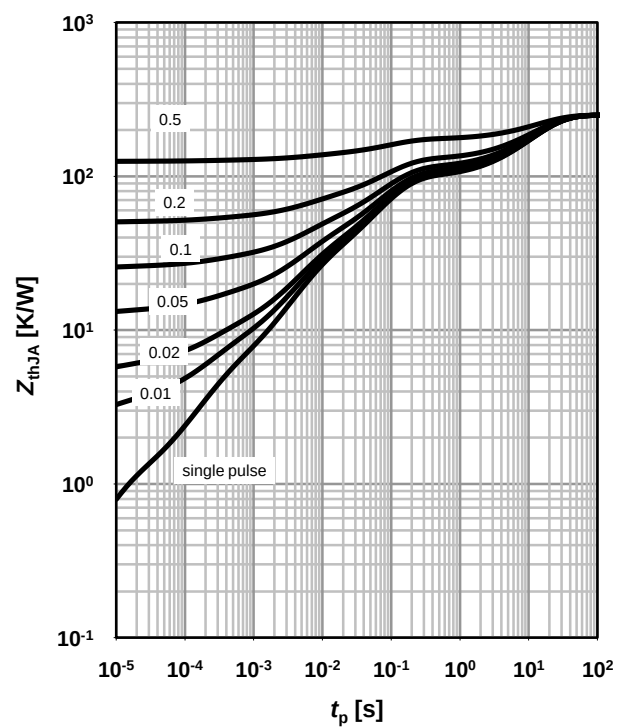
parameter: t_p



4 Max. transient thermal impedance

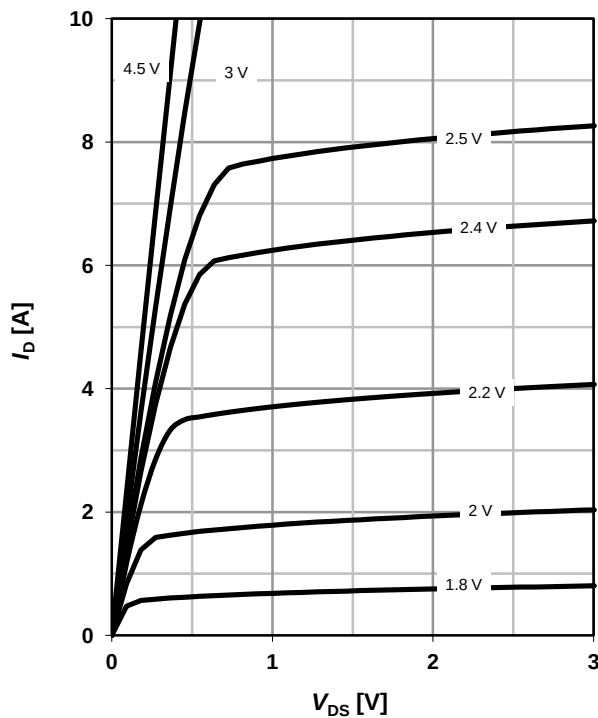
$$Z_{thJA} = f(t_p)$$

parameter: $D = t_p/T$



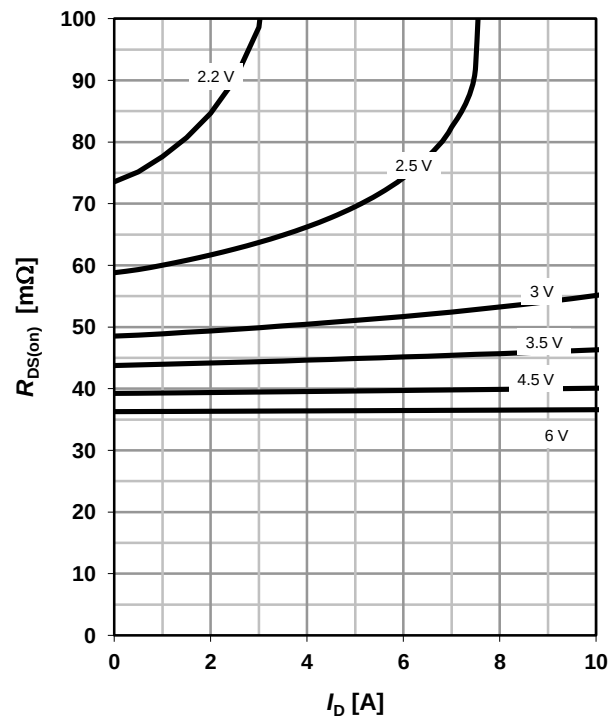
5 Typ. output characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

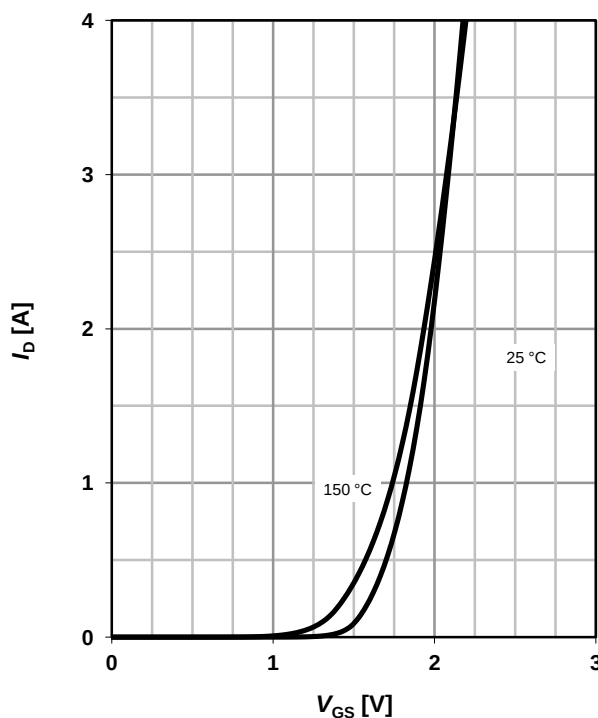
parameter: V_{GS}


6 Typ. drain-source on resistance

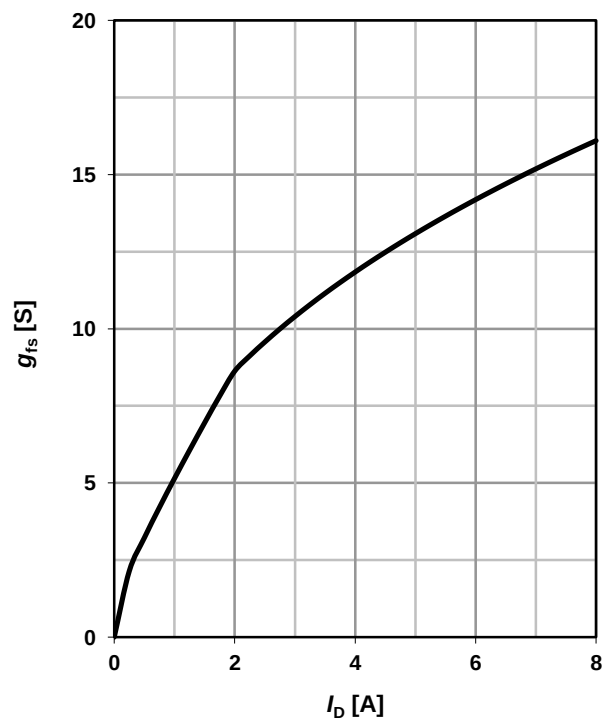
 $R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$

parameter: V_{GS}


7 Typ. transfer characteristics

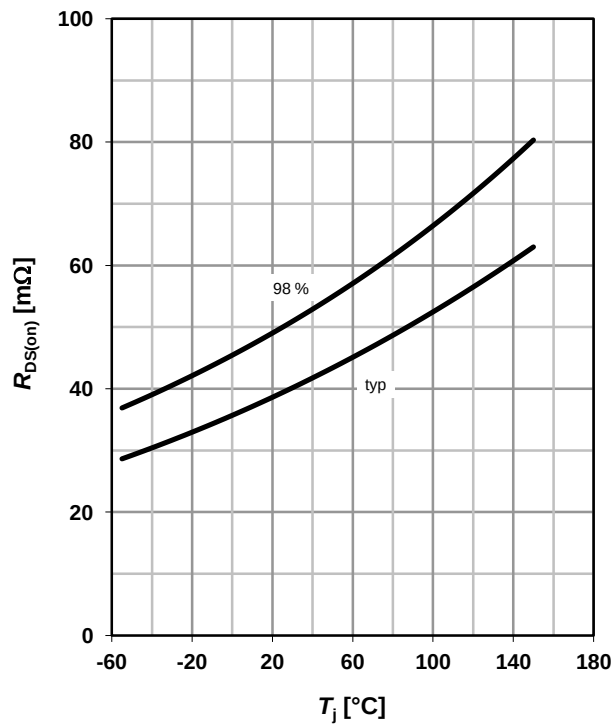
 $I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$


8 Typ. forward transconductance

 $g_{fs} = f(I_D); T_j = 25^\circ\text{C}$


9 Drain-source on-state resistance

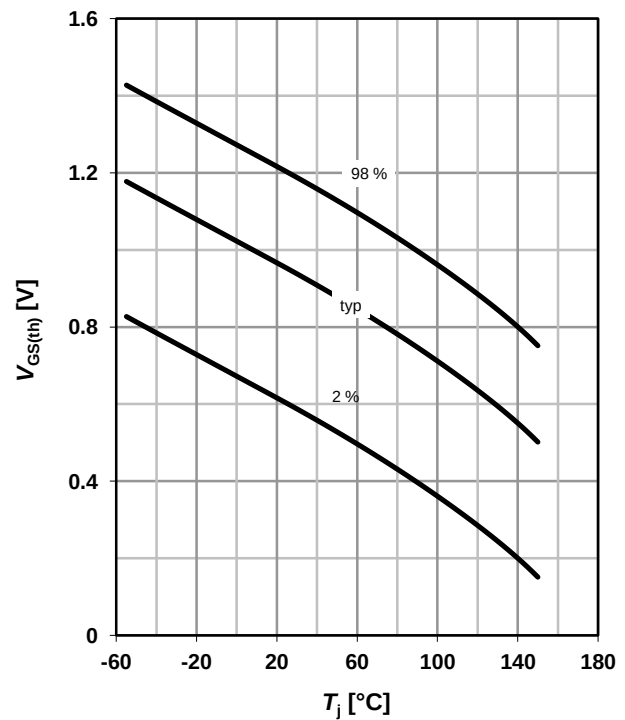
$$R_{DS(on)} = f(T_j); I_D = 2.5 \text{ A}; V_{GS} = 4.5 \text{ V}$$



10 Typ. gate threshold voltage

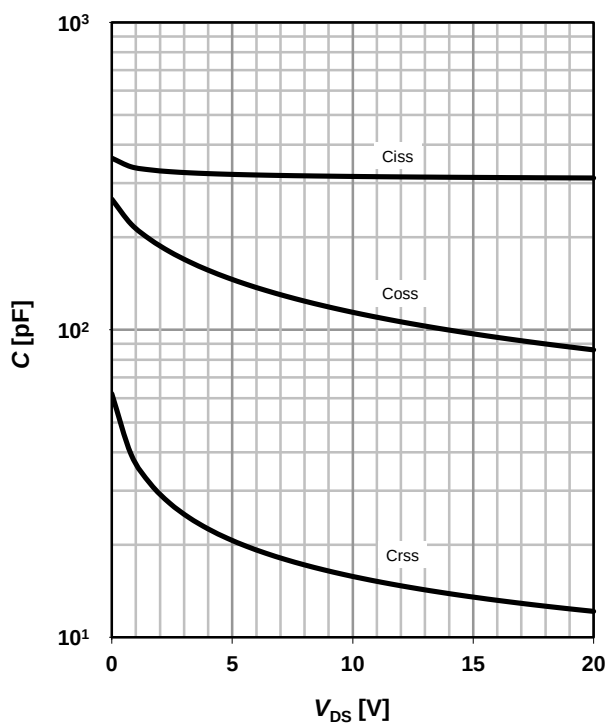
$$V_{GS(th)} = f(T_j); V_{DS} = V_{GS}; I_D = 11 \mu\text{A}$$

parameter: I_D



11 Typ. capacitances

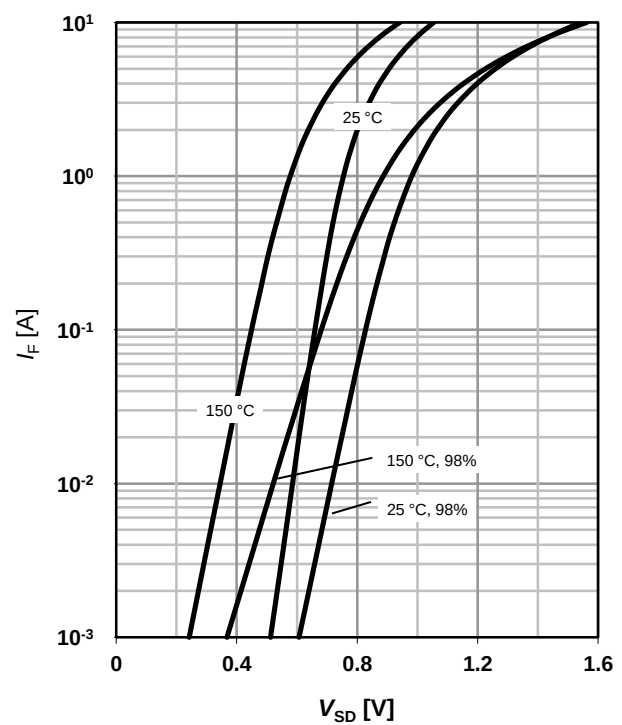
$$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}; T_j = 25^\circ\text{C}$$



12 Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

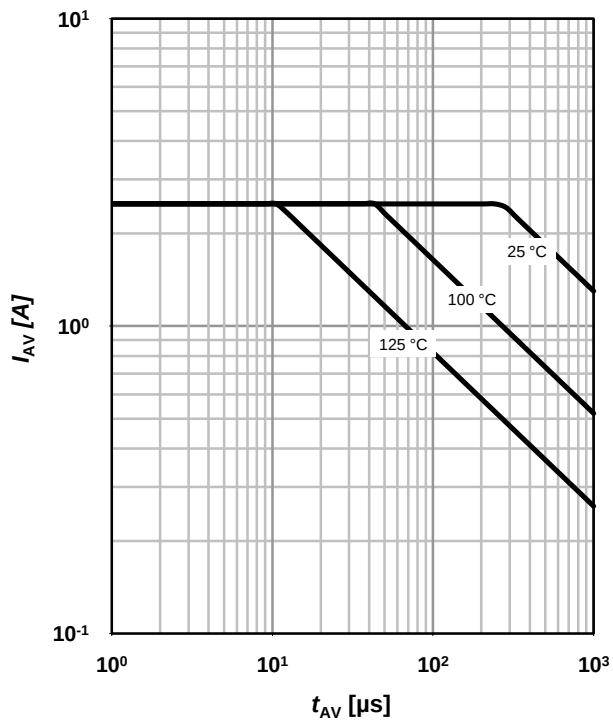
parameter: T_j



13 Avalanche characteristics

$$I_{AS}=f(t_{AV}); R_{GS}=25\ \Omega$$

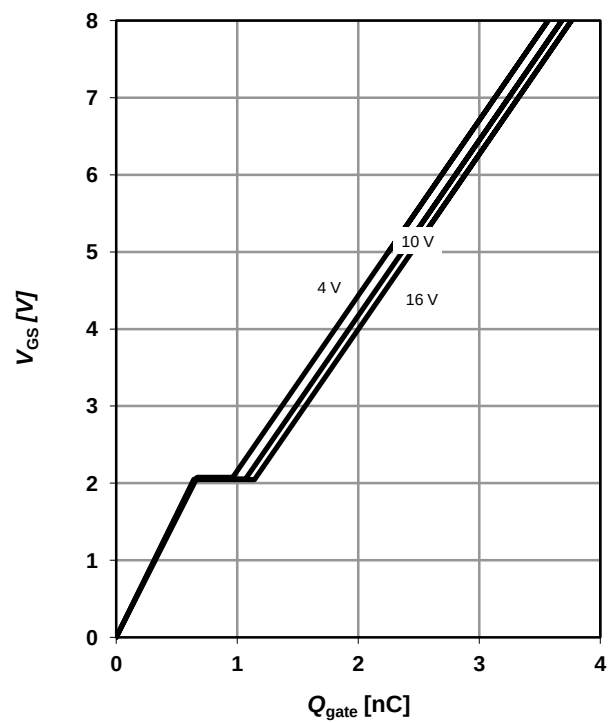
parameter: $T_{j(\text{start})}$



14 Typ. gate charge

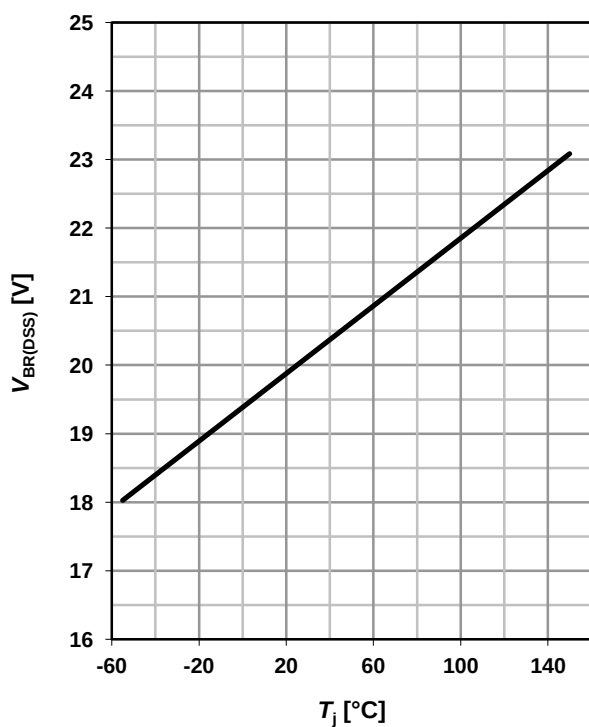
$$V_{GS}=f(Q_{\text{gate}}); I_D=2.5\ \text{A pulsed}$$

parameter: V_{DD}

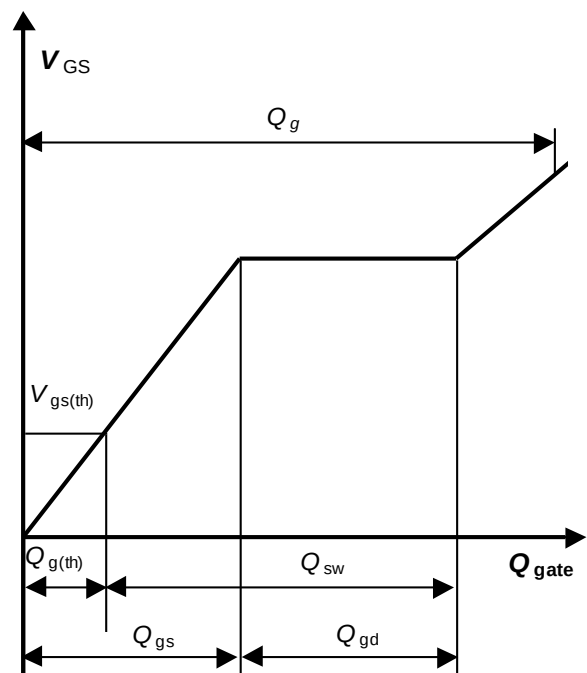


15 Drain-source breakdown voltage

$$V_{BR(DSS)}=f(T_j); I_D=250\ \mu\text{A}$$

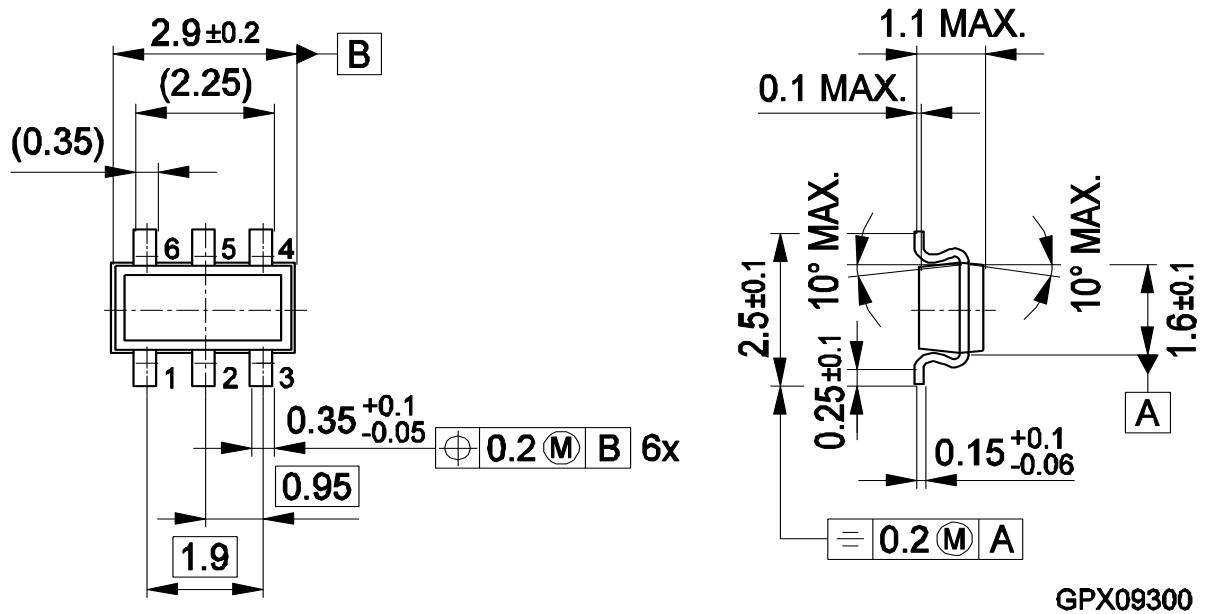


16 Gate charge waveforms

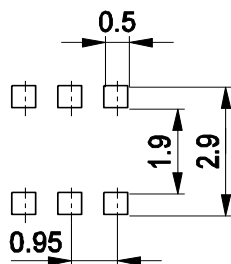


Package Outline:

TSOP6

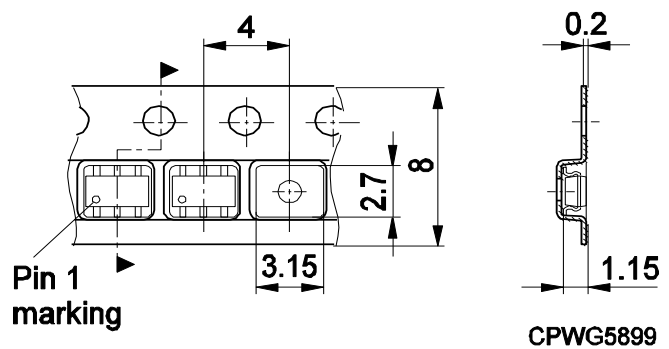


Footprint:



Remark: Wave soldering possible dep.
on customers process conditions
HLG09283

Packaging:



Dimensions in mm

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